



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Basol et al. Serial No.: 10/723,045 Filed: November 26, 2003 Title: Electrode Assembly For Electrochemical Processing Of Workpiece	Group Art Unit: 1742 Examiner: Docket: NT-285-US
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INFORMATION DISCLOSURE STATEMENT

US PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
NS	AA	6,365,017	April, 2002	Hongo et al.	In Serial No. 09/845,262
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Examiner Signature	/Nicholas Smith/	Date Considered	06/14/2006
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